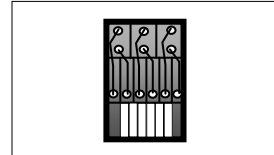
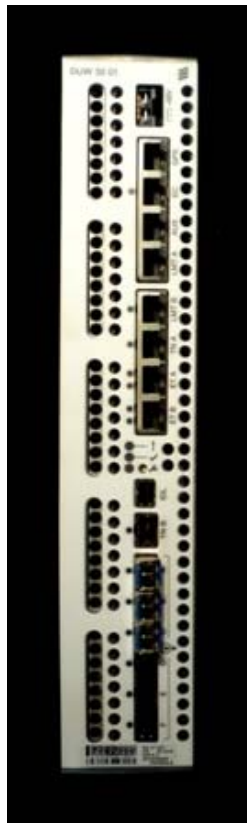


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Ericsson W-CDMA/HSPA Baseband Unit KDU 127 161/3 R3C Model DUW30 01

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